2020-2-27 Rev.2.0

RD Number: RD134

RD Title: TB67H302HG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VREG	1	0.1µF 100V	–	–	Chip capacitor		
2	C_VCC2	1	0.1µF 100V	–	–	Chip capacitor		
3	C_VREFA	1	0.1µF 100V	–	–	Chip capacitor		
4	C_VREFB	1	0.1µF 100V	–	–	Chip capacitor		
5	C_VCC1	1	100µF 50V	–	–	Electrolytic capacitor		
6	C_VDD	0	10µF 25V	–	–	Electrolytic capacitor		✓
7	CON2, CON3	2	Terminal block 2P	–	–	Terminal block 2P ×2		
8	OUT2B	1	Check terminal	–	–	Logic pin		
9	OUT1B	1	Check terminal	–	–	Logic pin		
10	OUT2A	1	Check terminal	–	–	Logic pin		
11	OUT1A	1	Check terminal	–	–	Logic pin		
12	RSA	1	Check terminal	–	–	Logic pin		
13	RSB	1	Check terminal	–	–	Logic pin		
14	Vreg	1	Check terminal	–	–	Logic pin		
15	VDD	1	Check terminal	–	–	Logic pin		
16	VCC	1	Check terminal	–	–	Logic pin		
17	ALERT1	1	Check terminal	–	–	Logic pin		
18	SELECT	1	Check terminal	–	–	Logic pin		
19	VrefA	2	Check terminal	–	–	Logic pin		
20	VrefB	1	Check terminal	–	–	Logic pin		
21	STBY	1	Check terminal	–	–	Logic pin		
22	IN1B	1	Check terminal	–	–	Logic pin		
23	IN2B	1	Check terminal	–	–	Logic pin		
24	IN1A	1	Check terminal	–	–	Logic pin		
25	IN2A	1	Check terminal	–	–	Logic pin		
26	PWMA	1	Check terminal	–	–	Logic pin		

27	PWMB	1	Check terminal	–	–	Logic pin		
28	OSC	1	Check terminal	–	–	Logic pin		
29	ALERT2	1	Check terminal	–	–	Logic pin		
30	GND1	1	Check terminal	–	–	Logic pin		
31	GND2	1	Check terminal	–	–	Logic pin		
32	GND3	1	Check terminal	–	–	Logic pin		
33	GND4	1	Check terminal	–	–	Logic pin		
34	GND5	1	Check terminal	–	–	Logic pin		
35	GND6	1	Check terminal	–	–	Logic pin		
36	GND7	1	Check terminal	–	–	Logic pin		
37	GND8	1	Check terminal	–	–	Logic pin		
38	GND9	1	Check terminal	–	–	Logic pin		
39	JP_VREG	1	Pin header 2P	–	–	Jumper		
40		1	Jumper socket	–	–	Short pin		
41	R_ALERT1	1	100kΩ 0.25W	–	–	Chip resistor		
42	R_ALERT2	1	100kΩ 0.25W	–	–	Chip resistor		
43	R_OSC	2	Socket pin	–	–	Socket pin		
44		1	51kΩ 0.25W	–	–	Leaded resistor		
45		0	51kΩ	–	–	Chip resistor		✓
46	R_VRF1	2	Socket pin	–	–	Socket pin		
47		0	Not mount	–	–	Leaded resistor		✓
48	R_VRF2	2	Socket pin	–	–	Socket pin		
49		0	Not mount	–	–	Leaded resistor		✓
50	R_VRF3	2	Socket pin	–	–	Socket pin		
51		0	Not mount	–	–	Leaded resistor		✓
52	R_VRF4	2	Socket pin	–	–	Socket pin		
53		0	Not mount	–	–	Leaded resistor		✓
54	RRSA	1	0.22Ω 1W	–	–	Chip resistor		
55		0	0.22Ω 1W	–	–	Leaded resistor		✓
56	RRSB	1	0.22Ω 1W	–	–	Chip resistor		
57		0	0.22Ω 1W	–	–	Leaded resistor		✓
58	SW3	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
59	SELECT	1	Jumper socket	–	–	Short pin	2.54mm pitch	
60	SW4	0	Pin header 3P	–	–	Jumper	2.54mm pitch	✓

61	VrefA	0	Jumper socket	–	–	Short pin	2.54mm pitch	✓
62	SW7	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
63	STBY	1	Jumper socket	–	–	Short pin	2.54mm pitch	
64	SW8	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
65	IN1B	1	Jumper socket	–	–	Short pin	2.54mm pitch	
66	SW9	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
67	IN2B	1	Jumper socket	–	–	Short pin	2.54mm pitch	
68	SW18	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
69	IN1A	1	Jumper socket	–	–	Short pin	2.54mm pitch	
70	SW19	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
71	IN2A	1	Jumper socket	–	–	Short pin	2.54mm pitch	
72	SW21	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
73	PWMA	1	Jumper socket	–	–	Short pin	2.54mm pitch	
74	SW22	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
75	PWMB	1	Jumper socket	–	–	Short pin	2.54mm pitch	
76	IC1	1	TB67H302HG	TB67H302HG	TOSHIBA	Motor driver IC	HZIP25	
77		1		17PC47 L25B		Heat sink		
78		2		M3X8(RO)		M3x8mm		
79		2		D3035-5110				

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